MOLD INVESTIGATION DECISION LOGIC NOTES:

1. Roughly approximate the total surface area of visible mold. Categorization of the remediation levels are sometimes borderline, so when trying to decide the category to apply, consider the extent of visible growth, such as a heavy blanket of growth on the surface, to barely visible. If heavy growth is apparent, consider moving up to the next level of protection.

2. Do not skip this step. Address the source of water or moisture problem or the mold will simply reappear.

3. Always protect the health and safety of the building occupants and remediators.

4. Mold may be hiding on the backside of drywall, vinyl wallpaper, or paneling, the top of ceiling tiles, the underside of carpets and pads. Check walls behind furniture, pipe chases and utility tunnels, porous thermal or acoustic liners inside ductwork, or check the rafters (due to roof leaks or insufficient insulation).

5. Utilize appendices B and C for remediation guidance. Use your best judgment during investigations, if not disturbing the mold you may need minimal to no PPE. Do not alarm building occupants unnecessarily, but protect yourself as necessary.

6. If the containment is working properly, the polyethylene sheeting will billow inwards on all surfaces. If it flutters or billows outward, containment has not been achieved, and you should find and correct the problem before starting your remediation activities. Confirm negative pressure with smoke tubes.

7. Select remediation personnel who have the experience and training needed to implement the remediation plan.

8. You must completely fix or eliminate the water or moisture problem to solve the problem.

9. You should revisit the site(s) approximately two weeks after remediation, and it should show no signs of water damage or mold growth.

10. If you discover hidden mold, revise your plan by reassessing the size of moldy area.

11. If you believe that you have a hidden mold problem, you may want to consider hiring an experienced mold investigative professional.